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TECHNOLOGY CENTER 2800

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Patent Application of:

Tai-Chong CHAI *et al.*

Serial No.: 09/497,421

Filed: February 2, 2000

For: LEAD FRAME FOR AN INTEGRATED  
CIRCUIT CHIP (SMALL WINDOW)

66286-002

Group Art Unit: 2815

Examiner: L. Cruz

Commissioner for Patents  
Washington, D.C. 20231

Via Facsimile  
703-746 3902

Sir:

**AMENDMENT**

In response to the Office Action of August 27, 2002, please amend the Application as follows:

**IN THE CLAIMS**

Please amend claims 1 and 12 as follows:

1. (Amended) A lead frame, for an integrated circuit chip having a frame engaging bottom surface for attachment to the frame by means of a chip attach material, said chip being formed with outer edges having defined dimensions, said frame comprising:

1) a unitary apertured frame having a central through aperture therein including a plurality of uniform sidebars each having an upper chip-supporting surface for engaging the bottom of the surface of the chip with the chip attach material therebetween,

each of said sidebars having an inner edge and an outer edge, said inner edges defining the central aperture,

said inner and outer edges being uniformly spaced apart defining therebetween a chip-support zone [for the frame] having defined dimensions,

**CERTIFICATE OF TRANSMISSION**

I hereby certify that this correspondence is being facsimile transmitted to the U.S. Patent and Trademark Office, Fax No 703/746/3902 on 11/27/02.

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